

Notice of References Cited

Application No.
09/450,632

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U.S. PATENT DOCUMENTS

*		DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
x	A	5,527,628	6/1996	Anderson et al	428	647
x	B	5,344,607	9/1994	Gonya et al	420	562
x	C	5,125,574	6/1995	Anderson et al	239	8
x	D	5,520,752	5/1996	Lucey, Jr et al	148	400
x	E	5,429,689	7/1995	Shangguan et al	148	400
x	F	5,066,544	11/1991	Betrabet et al	428	614
x	G	4,506,822	3/1985	Hammersand et al	228	200
x	H	4,358,884	11/1982	Harvey et al	29	402.18
x	I	4,248,905	2/1981	Harvey et al	427	11
x	J	3,481,795	12/1969	Lane	136	237
x	K	5,094,700	3/1992	Sekhar	148	12.9
x	L	5 817 194	10/1998	Nagai et al	148	400
	M					

FOREIGN PATENT DOCUMENTS

*		DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS	SUBCLASS
	N						
	O						
	P						
	Q						
	R						
	S						
	T						

NON-PATENT DOCUMENTS

*		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
x	U	Kuo et al, "Fatigue Deformation of In-situ Composite Solders", Microstructures and Mechanical Properties of Aging Material, pp 417-423.	1993
x	V	Kuo et al, "Tensile and Creep Properties of In-situ Composite Solders", Microstructures and Mechanical Properties of Aging Material, pp 409-415.	1993
x	W	Wienbel et al, "Creep-fatigue Interaction in Eutectic Lead-Tin Solder Alloy" Journal of Materials Science, Vol 22, pp3901-3906.	1987
x	X	Wasynczuk et al, "Shear Creep of Cu6Sn5/Sn-Pb Eutectic Composites", Proceeding of Technical Program National Electronic Packaging and Production Conference, Vol III, pp1245-1255.	1992

* A copy of this reference is not being furnished with this Office action.
(See Manual of Patent Examining Procedure, Section 707.05(a).)

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	N						
	O						
	P						
	Q						
	R						
	S						
	T						

NON-PATENT DOCUMENTS

*		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
x	U	Tien et al, "Creep-Fatigue Interactions in Solders", IEEE, Vol 12 No 4, pp 502-505.	1989
x	V	Shine et al, "Fatigue of Solder Joints in Surface Mount Devices", Low Cycle Fatigue ASTM STP 942, pp 588-610.	1988
x	W	Shangguan et al, Evaluation of Lead-Free Eutectic Sn-Ag Solder for Automotive Electronics Packaging Applications", IEEE, pp 25-37.	1994
x	X	Sastry et al, "Microstructures and Mechanical Properties of In-situ Composite Solders", Proceeding of Technical Program National Electronic Packaging and Production Conference, Vol III, pp 1266-1275.	1992

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	N						
	O						
	P						
	Q						
	R						
	S						
	T						

NON-PATENT DOCUMENTS

*		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
x	u	Pinizzotto et al, "Microstructural Development in Composite Solders Caused by Long Time High Temperature Annealing", Proceeding of Technical Program NEPCON WEST, Anaheim, CA , pp 1284-1298.	1992
✓	v	McCormack et al, "Enhanced Solder Alloy Performance by Magnetic Dispersions", IEEE, Vol 17 A, No 3, pp 452-457.	1994
x	w	McCormack et al, "The Design and Properties of New, Pb-Free Solder Alloys", IEEE/CPMT Int'l Electronic Manufacturing Technology Symposium, pp 7-14.	1994
x	x	Marshall et al, "Microcharacterization of Composite Solders", Proceeding of Technical Program National Electronic Packaging and Production Conference, Vol III, pp 1278-1283.	1992

* A copy of this reference is not being furnished with this Office action.
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FOREIGN PATENT DOCUMENTS

*		DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS	SUBCLASS
	N						
	O						
	P						
	Q						
	R						
	S						
	T						

NON-PATENT DOCUMENTS

*		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
x	U	Marshall et al, "Composite Solders", IEEE Vol 14, No 4, pp 698-702.	1991
x	V	Lau et al, "Solder Joint Fatigue in Surface Mount Technology: State of the Art", Solid State Technology, pp 91-104.	1985
x	W	Frear et al, "Thermal Fatigue in Solder Joints", Journal of Metals, pp 18-22.	1988
x	X	Clough et al, "Preparation and Properties of Reflowed Paste and Bulk Composite Solder", Proceedings NEPCON West Cahners Exhibition Group, pp 1256-1265.	1992

* A copy of this reference is not being furnished with this Office action.
(See Manual of Patent Examining Procedure, Section 707.05(a).)

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	N						
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	P						
	Q						
	R						
	S						
	T						

NON-PATENT DOCUMENTS

*		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
x	U	Betrabet et al, "Towards Increased Fatigue Resistance in Sn-Pb Solders by Dispersion Strengthening", Proceeding of Technical Program National Electronic Packaging and Production Conference, Vol III, pp1276-1277.	1992
x	V	Betrabet et al, "Processing Dispersion-Strengthened Sn-Pb Solders to Achieve Microstructural Refinement and Stability", Script Metallurgica et Materialia, Vol 25, pp. 2323-2328.	1991
x	W	Attarwala et al, "Confirmation of Creep and Fatigue Damage in PB/Sn Solder Joints" Journal of Electronic Packaging, Vol 114.	1992
x	X	Ho et al, "Carbon Fiber Reinforced Tin-Lead Alloy as a Low Thermal Expansion Solder Preform", J. Mater. Res. Vol 5, No. 6, pp 1266-1270.	1990

* A copy of this reference is not being furnished with this Office action.
(See Manual of Patent Examining Procedure, Section 707.05(a).)